



# 31<sup>st</sup> International Conference on Microelectronic Test Structures

March 19-22, 2018, Courtyard Marriott Downtown, Austin, Texas

Looking for the best opportunity to present and discuss your ideas and results about test structures, measurements and characterization? This is your chance! Join the 31<sup>st</sup> ICMTS conference.

A **Tutorial Short Course** will precede the conference sessions.

Several of the best measurement, equipment, design, and manufacturing experts, will participate to the **equipment exhibition** and presentations.

The conference will bring together designers and users of test structures to discuss recent developments and future directions, in a **one-track program**, with convivial breaks allowing attendees to discuss and exchange viewpoints and challenges.

A **Best Paper** award will be presented by the Technical Program Committee.

The conference is **sponsored by the IEEE Electron Devices Society** and published papers will be posted to **IEEE Xplore®**.

Original papers are solicited presenting new developments in **topics relevant to ICMTS, including but not limited to, test structures measurements and results, about:**

- R&D and manufacture of ICs, MEMS, sensors, actuators, photonics, bioelectronics, etc.
- Material – Process – New Technology Characterizations
- New devices – Memory Cells – Arrays
- DC – Pulsed – RF: measurements techniques and applications
- Design Methods – Verification – Metrology
- Devices and Circuit Modeling – Parameter Extraction
- Matching – Variability
- Reliability – Wafer-level / thermal Product Failure Analysis and prediction
- Yield Enhancement – Production Process Control
- Measurements – Statistical Characterization – Probing – Throughput - Analysis – Strategies
- **NEW:** Within-die circuits for process characterization / monitoring
- **NEW:** Design enablement – Characterization and validation of digital and analog libraries

Author's abstract submission consists in up to four pages in PDF format (font-embedded).

The first page includes a title, a 50-word summary, author name(s), the full address, fax number, and e-mail address of the lead author, and preference for oral or poster session presentation, if any. The body of the abstract should consist of one page of text (800 to 1000 words) and up to two pages containing major figures and tables.

The selection process will be based on the technical merit and will be highly weighted in **favor of papers with high test structure content**, including measured data and analysis.

**The submission deadline is extended to November 10, 2017.**

Submission information is available at <http://icmts.if.t.u-tokyo.ac.jp/>

Notice of **paper acceptance**, will be sent to the selected authors by **December 8, 2017**, with instructions for manuscript preparation for the conference proceedings.

The **deadline** for submission of the **final paper** will be **January 26, 2018**.

You may care to join the ICMTS group at [www.linkedin.com](http://www.linkedin.com).

Details of the venue, hotel, registration, etc. will be posted at the ICMTS 2018 official web site: <http://icmts.if.t.u-tokyo.ac.jp/>

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